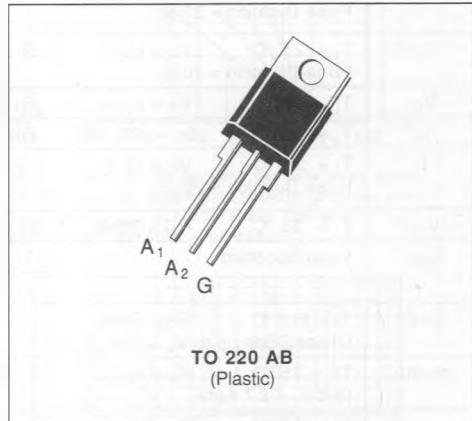


## SENSITIVE GATE TRIACS

- GLASS PASSIVATED CHIP
- $I_{GT}$  SPECIFIED IN FOUR QUADRANTS
- AVAILABLE IN INSULATED VERSION → BTA SERIES (INSULATING VOLTAGE 2500 V<sub>RMS</sub>) OR IN UNINSULATED VERSION → BTB SERIES
- UL RECOGNIZED FOR BTA SERIES (E81734)



### DESCRIPTION

New range suited for applications such as phase control and static switching.

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state Current (360° conduction angle)	6	A
$I_{TSM}$	Non Repetitive Surge Peak on-state Current (T <sub>j</sub> initial = 25 °C - Half sine wave)	t = 8.3 ms	A
		t = 10 ms	
$I^2t$	$I^2t$ Value for Fusing	18	A <sup>2</sup> s
$di/dt$	Critical Rate of Rise of on-state Current (1)	10	A/ $\mu$ s
		50	
$T_{stg}$ T <sub>j</sub>	Storage and Operating Junction Temperature Range	- 40 to 150	°C
		- 40 to 110	°C

Symbol	Parameter	BTA/BTB 06-					Unit
		200D	400D	600D	700D	800D	
V <sub>DRM</sub>	Repetitive Peak off-state Voltage (2)	200	400	600	700	800	V

(1)  $I_G = 100$  mA    $di/dt = 1$  A/ $\mu$ s

(2) T<sub>j</sub> = 110 °C.

### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R <sub>th</sub> (j-a)	Junction to Ambient	60	°C/W
R <sub>th</sub> (j-c) DC	Junction to Case for DC	5.8	°C/W
R <sub>th</sub> (j-c) AC	Junction to Case for 360 ° Conduction Angle (F = 50 Hz)	4.3	°C/W

**GATE CHARACTERISTICS** (maximum values)

$$P_{GM} = 40 \text{ W } (t_p = 10 \mu\text{s}) \quad I_{GM} = 4 \text{ A } (t_p = 10 \mu\text{s})$$

$$P_G(\text{AV}) = 1 \text{ W} \quad V_{GM} = 16 \text{ V } (t_p = 10 \mu\text{s})$$

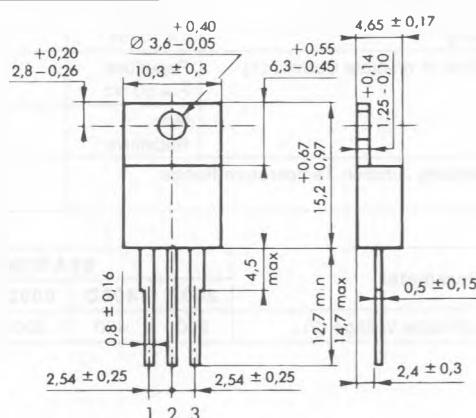
**ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
I <sub>GT</sub>	T <sub>j</sub> = 25 °C Pulse Duration > 20 µs	V <sub>D</sub> = 12 V	R <sub>L</sub> = 33 Ω	I-II-III IV			5	mA
V <sub>GT</sub>	T <sub>j</sub> = 25 °C Pulse Duration > 20 µs	V <sub>D</sub> = 12 V	R <sub>L</sub> = 33 Ω				10	
V <sub>GD</sub>	T <sub>j</sub> = 110 °C	V <sub>D</sub> = V <sub>DRM</sub>	R <sub>L</sub> = 3.3 kΩ	I-II-III-IV	0.2			V
I <sub>H</sub> *	T <sub>j</sub> = 25 °C	I <sub>T</sub> = 100 mA	Gate Open				15	mA
I <sub>L</sub>	T <sub>j</sub> = 25 °C Pulse Duration > 20 µs	V <sub>D</sub> = 12 V	I <sub>G</sub> = 20 mA	I-III-IV II	15			mA
V <sub>TM</sub> *	T <sub>j</sub> = 25 °C	I <sub>TM</sub> = 8.5 A	t <sub>p</sub> = 10 ms				1.65	
I <sub>DRM</sub> *	V <sub>DRM</sub> Specified	T <sub>j</sub> = 25 °C T <sub>j</sub> = 110 °C					0.01	mA
dV/dt*	T <sub>j</sub> = 110 °C Linear Slope up to V <sub>D</sub> = 67 % V <sub>DRM</sub>	Gate Open					0.75	
(dV/dt) <sub>c</sub> *	T <sub>C</sub> = 75 °C (dV/dt) <sub>c</sub> = 2.7 A/ms	V <sub>D</sub> = V <sub>DRM</sub>	I <sub>T</sub> = 8.5 A				1	V/µs
t <sub>gt</sub>	T <sub>j</sub> = 25 °C I <sub>G</sub> = 20 mA	V <sub>D</sub> = V <sub>DRM</sub>	I <sub>T</sub> = 8.5 A	I-II-III-IV		2		µs

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>.

**PACKAGE MECHANICAL DATA**

TO 220 AB Plastic



Triac : 1 2 3 = A<sub>1</sub> A<sub>2</sub> G

Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g.

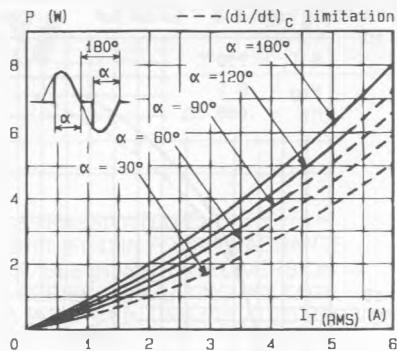


Fig.1 - Maximum mean power dissipation versus RMS on-state current ( $f = 60$  Hz).

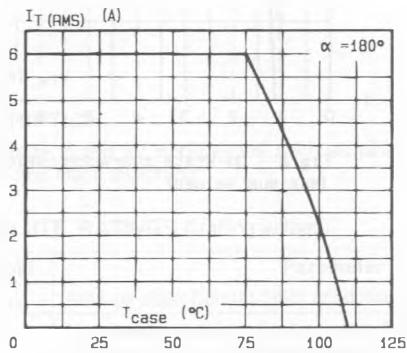


Fig.3 - RMS on-state current versus case temperature.

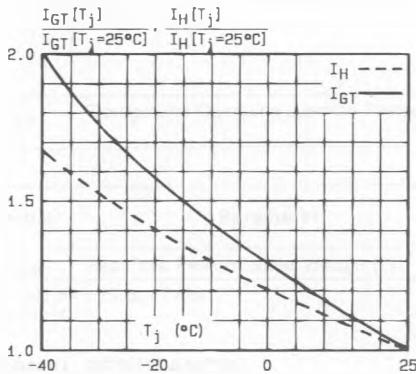


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

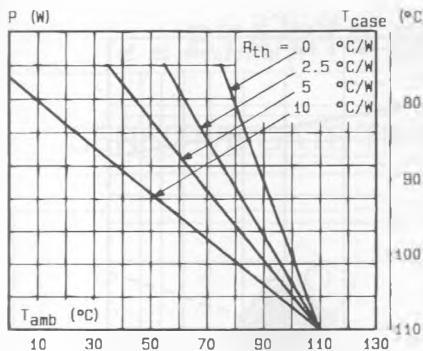


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact.

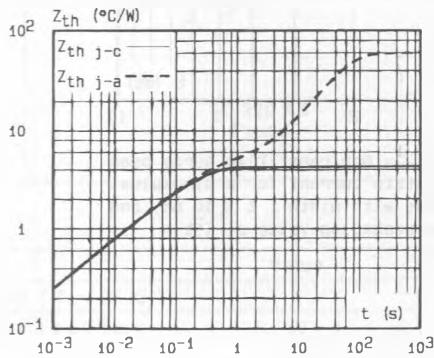


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

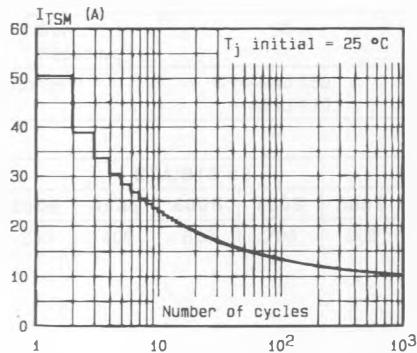


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

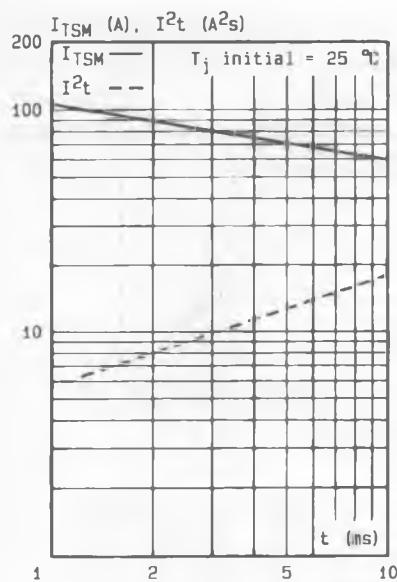


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .

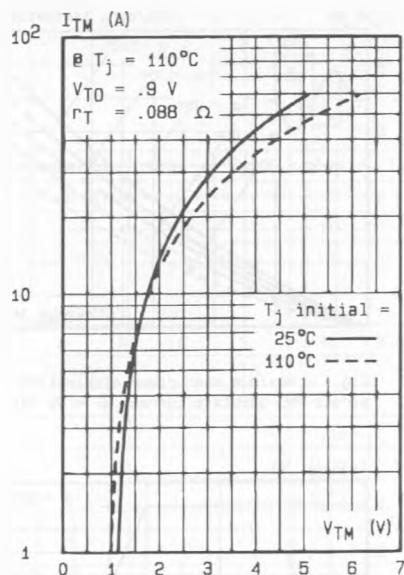


Fig.8 - On-state characteristics (maximum values).